

Features

- The plastic package carries UL Flammability Classification 94V-0
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed:260°C/10 seconds at terminals



Mechanical Characteristics

- Case: SMAF package molded plastic body over passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.0012 ounce, 0.034 grams

Absolute Maximum Ratings and Electrical Parameters (TA=25°C unless otherwise specified)

PARAMETER	SYMBOL	H1AF	H1BF	H1DF	H1GF	H1JF	H1KF	H1MF	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I_{AV}	1							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30							A
Maximum instantaneous forward voltage at 1A	V_F	1		1.4		1.7		V	
Maximum DC reverse current at rated DC blocking voltage	$T_A=25^\circ\text{C}$	I_R	5						μA
	$T_A=100^\circ\text{C}$	I_{RT}	50						μA
Maximum reverse recovery time ^(NOTE 1)	t_{rr}	50				75			ns
Typical junction capacitance ^(NOTE 2)	C_J	15							pF
Typical Thermal Resistance Junction to Ambient ^(NOTE3)	$R_{\theta JA}$	75							$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Lead ^(NOTE3)	$R_{\theta JL}$	22							$^\circ\text{C/W}$
Operating Temperature Range	T_J	-55 to 150							$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to 150							$^\circ\text{C}$

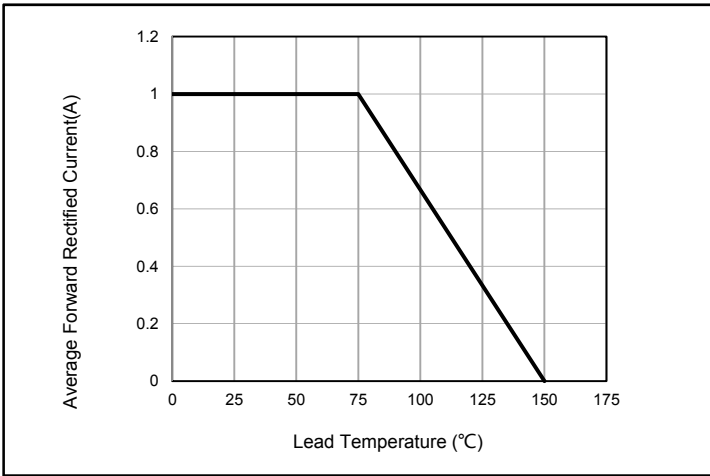
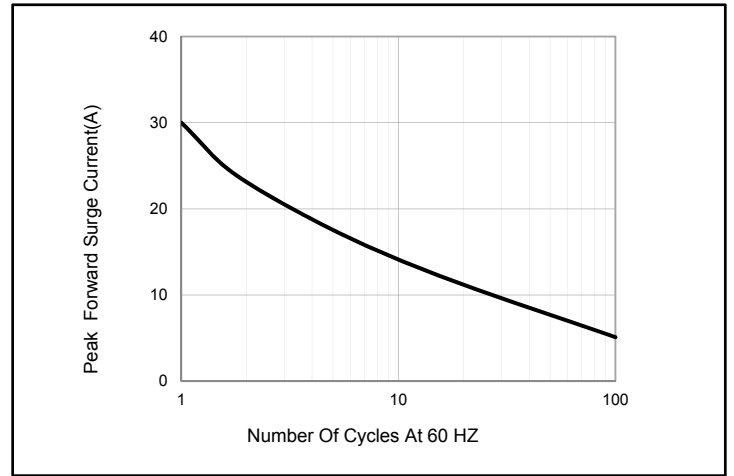
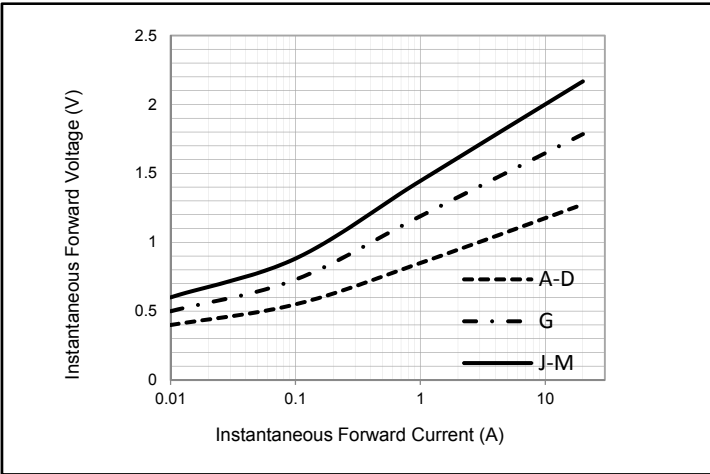
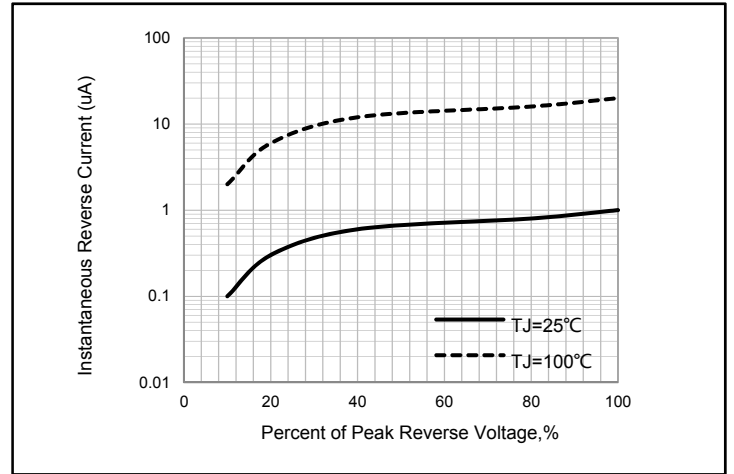
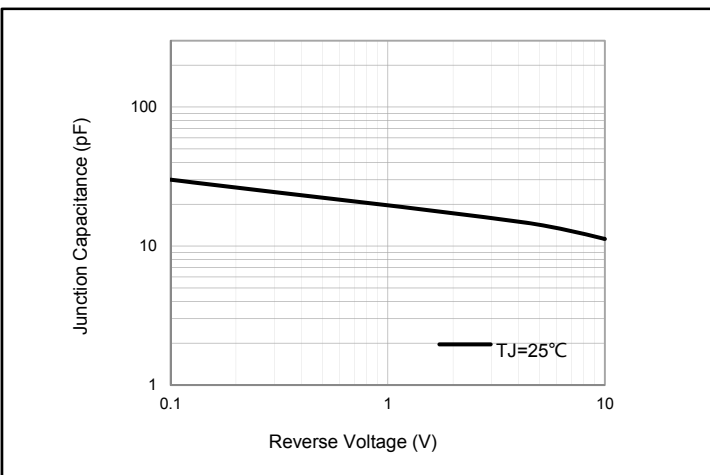
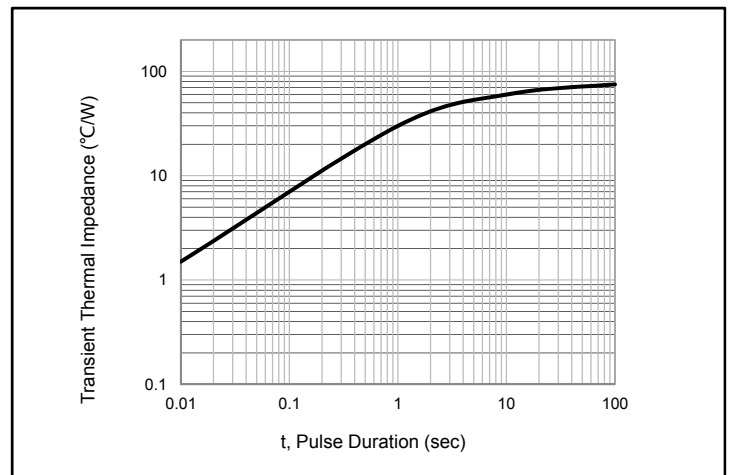
Note1: Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$

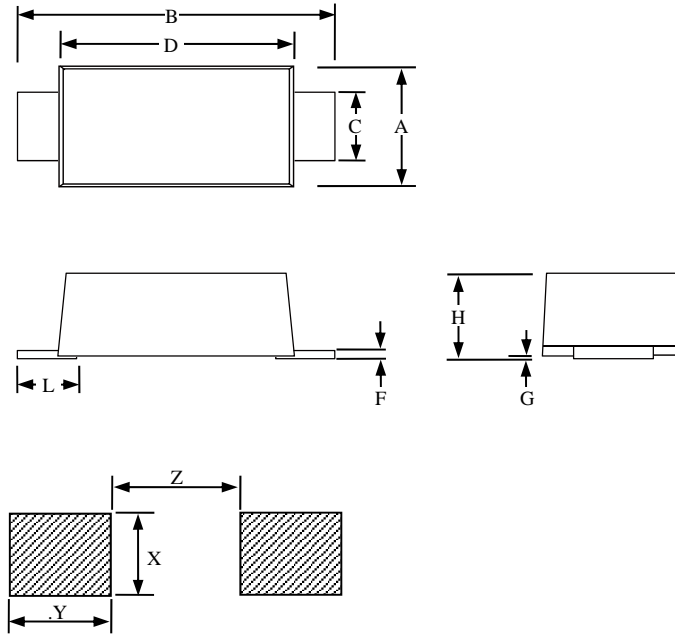
Note2: Measured at 1MHz and applied reverse voltage of 4.0V DC.

Note3: PCB. mounted with 5×5mm copper pad areas

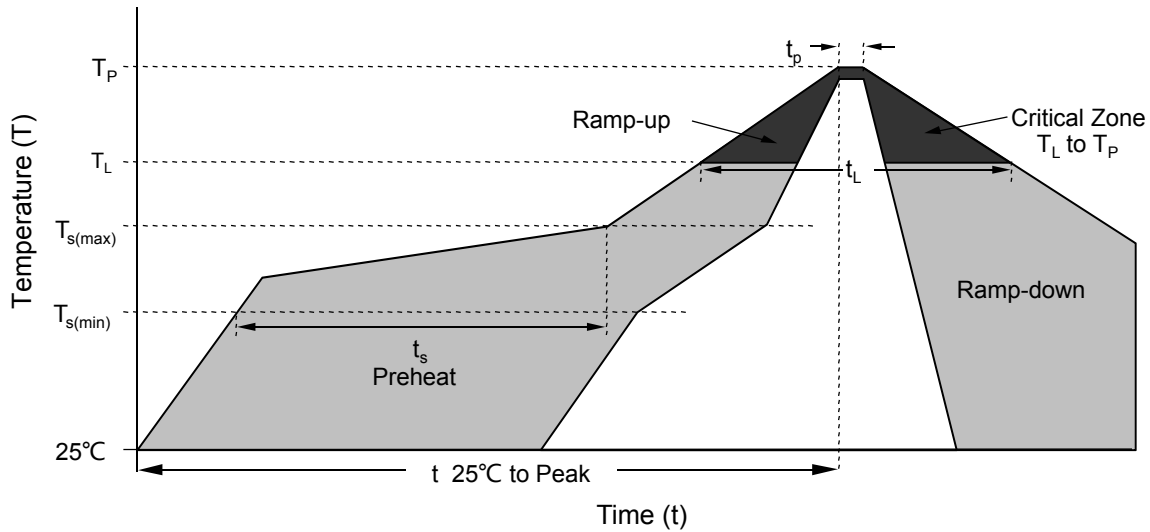
Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SMAF	Tape/Reel, 11" reel	5000	EIA-481-1
	Tape/Reel, 7" reel	3000	EIA-481-1

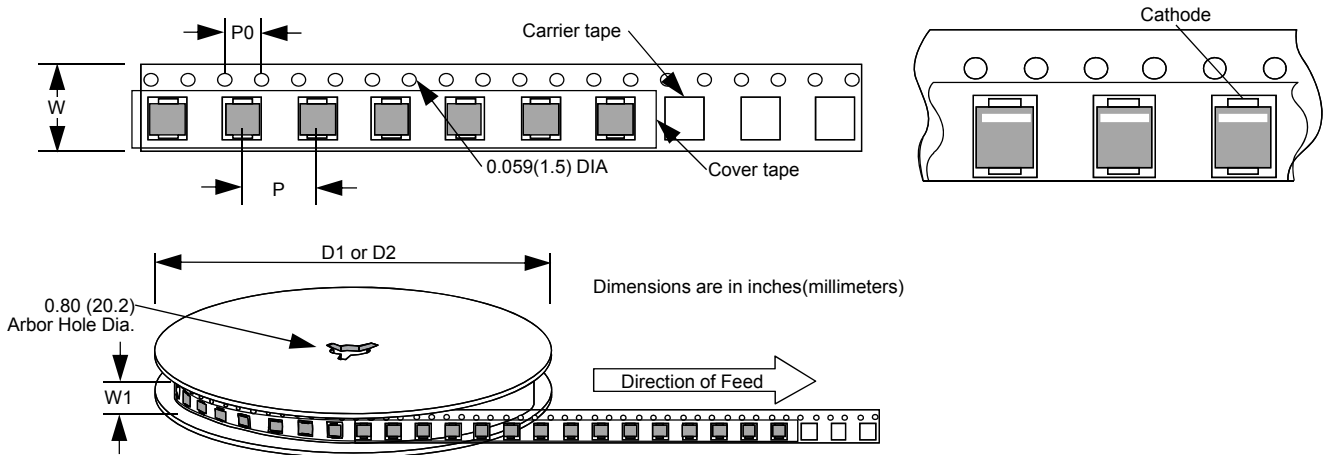

Fig. 1 - Forward Current Derating Curve

Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

Fig. 3 - Typical Instantaneous Forward Characteristics

Fig. 4 - Typical Reverse Characteristics

Fig. 5 - Typical Junction Capacitance

Fig. 6 - Typical Transient Thermal Impedance



SMAF						
Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.094		0.11	2.4		2.8
B	0.173		0.189	4.4		4.8
C	0.051		0.059	1.3		1.5
D	0.128		0.144	3.25		3.65
L	0.028		0.047	0.7		1.2
F	0.006		0.012	0.15		0.3
G	-		0.004	-		0.1
H	0.043		0.055	1.1		1.4
X		0.067			1.7	
Y		0.098			2.5	
Z		0.059			1.5	



Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (t_L)	60 – 150 secs
Peak Temperature (T_P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 secs
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (t)		8 minutes Max.
Do not exceed		260°C



Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
P		0.157			4	
P0		0.157			4	
W		0.472			12	
W1		0.492			12.5	
D1		7			177.8	
D2		11			279.4	

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